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2016年5月

FGA30S120P

1300 V、 30 A 阳极短路 IGBT

特性

- 高速开关
- 低饱和电压: V_{CE(sat)} =1.75 V @ I_C=30 A
- 高输入阻抗
- 符合 RoHS 标准

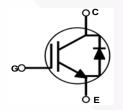
应用

• 感应加热,微波炉

概述

飞兆半导体的阳极短路沟道 IGBT 采用先进的场截止沟道和阳极 短路技术,为软开关应用提供卓越的导通和开关性能。该器件可 并联配置,具有极佳的雪崩能力。该器件为感应加热和微波炉而 设计。





绝对最大额定值 Tc= 25℃ 除非另有说明

符号	说明		额定值	单位
V _{CES}	集电极 - 发射极之间电压		1300	V
V_{GES}	栅极一发射极间电压		±25	٧
I _C	集电极电流	@ $T_C = 25^{\circ}C$	60	Α
	集电极电流	@ $T_C = 100^{\circ}C$	30	Α
I _{CM (1)}	集电极脉冲电流		150	Α
I _F	二极管正向连续电流	@ T _C = 25°C	60	Α
I _F	二极管正向连续电流	@ T _C = 100°C	30	Α
P_{D}	最大功耗 @ T _C = 25°C		348	W
. 0	最大功耗	@ T _C = 100°C	174	W
T_J	工作结温		-55 至 +175	°C
T _{stg}	存储温度范围		-55 至 +175	°C
T _L	用于焊接 的最大引脚温度,距离外壳 1/8",	持续 5 秒	300	°C

热性能

符号	参数	典型值	最大值	单位
		光工匠		
$R_{\theta JC}(IGBT)$	结点 - 壳体的热阻		0.43	°C/W
$R_{\theta JA}$	结至环境热阻		40	°C/W

注意: 1: 受限于最大结温

封装标识与定购信息

器件编号	顶标	封装	包装方法	卷尺寸	带宽	数量
FGA30S120P	FGA30S120P	TO-3P	塑料管	不适用	不适用	30

IGBT 电气特性 TC = 25℃ 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV _{CES}	Collector to Emitter Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	1300	_	_	V
ΔBV _{CES} / ΔΤ _J	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_C = 1 \text{ mA}$	-	1.3	-	V/°C
I _{CES}	集电极切断电流	V _{CE} = 1300, V _{GE} = 0 V	-	-	1	mA
I _{GES}	G-E 漏电流	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±500	nA
导通特性				l		
V _{GE(th)}	G-E 阈值电压	$I_C = 30 \text{ mA}, V_{CE} = V_{GE}$	4.5	6.0	7.5	V
- (*)		I _C = 30 A, V _{GE} = 15 V T _C = 25°C	-	1.75	2.3	V
V _{CE(sat)}	集电极 - 发射极间饱和电压	I _C = 30 A, V _{GE} = 15 V, T _C = 125°C	-	1.85	-	V
		I _C = 30 A, V _{GE} = 15 V, T _C = 175°C	-	1.9	-	V
V_{FM}	二极管正向电压	I _F = 30 A, T _C = 25°C	-	1.7	2.2	V
FIVI	—1以旨止凹圯止 	I _F = 30 A, T _C = 175°C	-	2.1	-	V
动态特性	給入中穴			3345	_	nF
C _{ies}	输入电容	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$	-	3345	-	pF _
Coes	输出电容	f = 1 MHz	-	75	-	pF
C _{res}	反向传输电容		-	60	-	pF
开关特性						
t _{d(on)}	导通延迟时间		-	39	-	ns
t _r	上升时间		- /	360	-	ns
t _{d(off)}	关断延迟时间	$V_{CC} = 600 \text{ V}, I_{C} = 30 \text{ A},$	-	620	-	ns
t _f	下降时间	R _G = 10 Ω, V _{GE} = 15 V,	-	160	-	ns
E _{on}	导通开关损耗	· 感性负载 , T _C =25°C	-	1.3	-	mJ
E _{off}	关断开关损耗		-	1.22	-	mJ
E _{ts}	总开关损耗		-	2.52	-	mJ
t _{d(on)}	导通延迟时间		-	38	-	ns
t _r	上升时间		-	375	-	ns
t _{d(off)}	关断延迟时间	$V_{CC} = 600 \text{ V}, I_{C} = 30 \text{ A},$	-	635	-	ns
t _f	下降时间	$R_G = 10 \Omega, V_{GE} = 15 V,$ 电阻性负载, $T_C = 175$ °C	-	270	-	ns
E _{on}	导通开关损耗		-	1.59	-	mJ
E _{off}	关断开关损耗		-	1.78	-	mJ
E _{ts}	总开关损耗		-	3.37	-	mJ
Q _g	总栅极电荷		-	78	-	nC
Q _{ge}	栅极一发射极间电荷	$V_{CE} = 600 \text{ V}, I_{C} = 30 \text{ A},$	=	4.2	-	nC
Q _{gc}	栅极一集电极间电荷	V _{GE} = 15 V	-	33.3	-	nC

典型性能特征

图 1. 典型输出特性

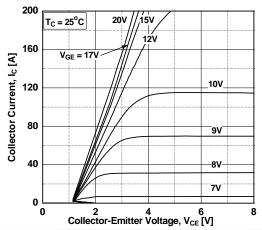


图 3. 典型饱和电压特性

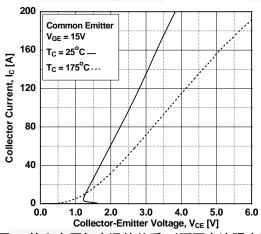


图 5. 饱和电压与壳温的关系 (不同电流强度下)

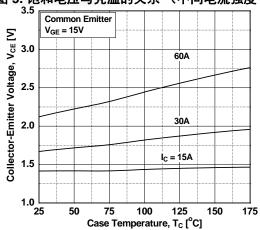


图 2. 典型输出特性

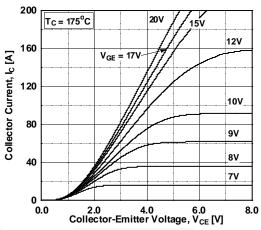


图 4. 传输特性

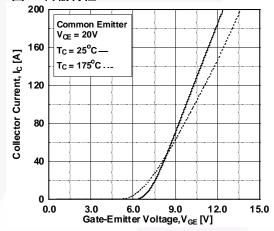
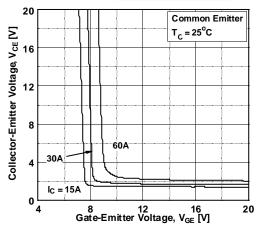


图 6. 饱和电压与 VgE 的关系



典型性能特征

图 7. 饱和电压与 VgE 的关系

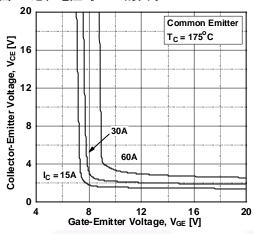


图 8. 电容特性

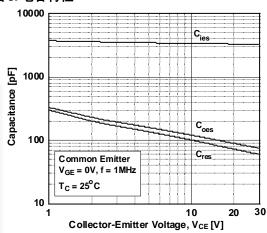


图 9. 栅极电荷特性

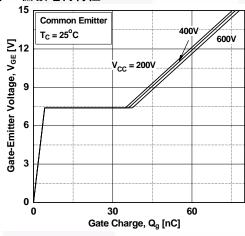


图 10. SOA 特性

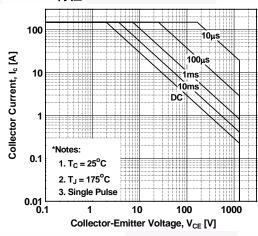


图 11. 导通特性与栅极电阻的关系

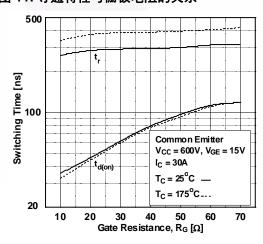
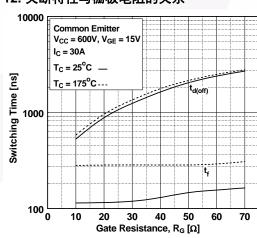


图 12. 关断特性与栅极电阻的关系



典型性能特征

图 13. 导通特性与集电极电流的关系

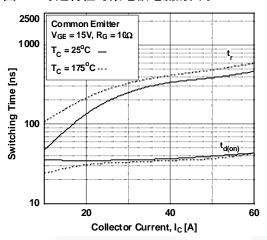


图 14. 关断特性与集电极电流的关系

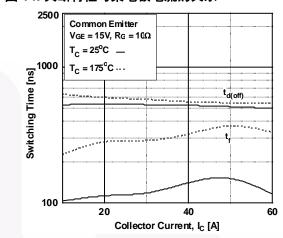


图 15. 开关损耗与栅极电阻的关系

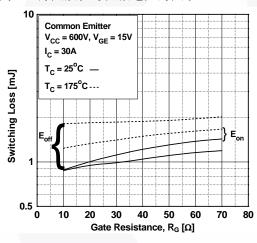


图 16. 开关损耗与集电极电流的关系

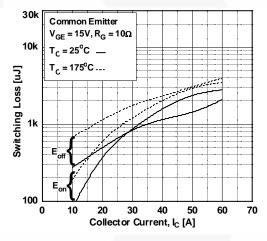


图 17. 关断开关 SOA 特性

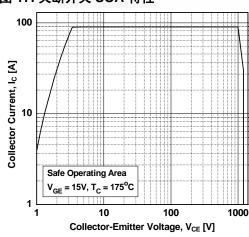


图 18. 正向特性

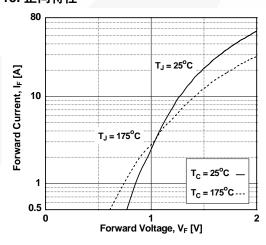
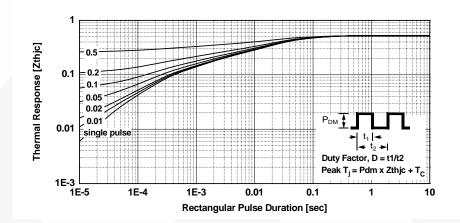
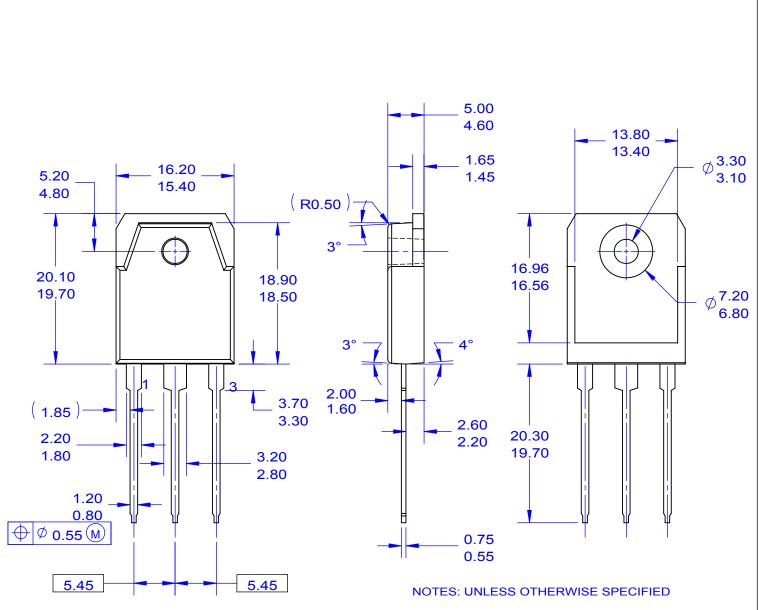
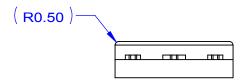


图 19.IGBT 的瞬态热阻抗







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